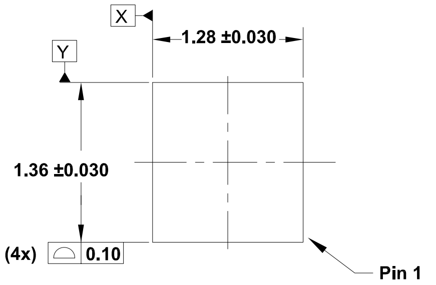
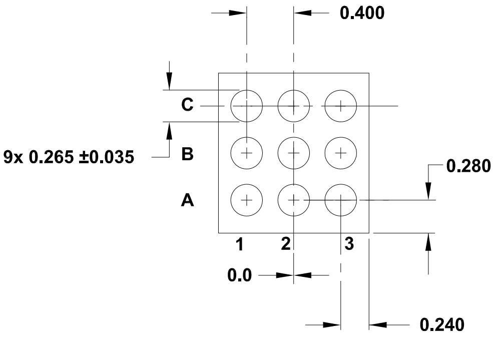
Package Outline Drawing

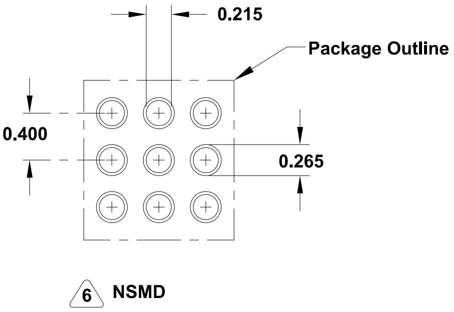
W3x3.9
9 Ball Wafer Level Chip Scale Package (WLCSP 0.4mm Pitch)
Rev 1, 3/2021



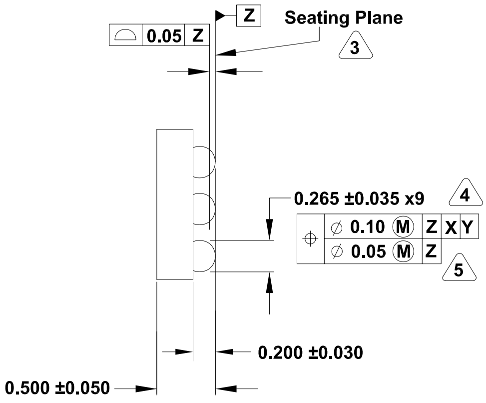
Top View



Bottom View



Recommended Land Pattern



Side View

NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerances per ASME Y14.5-1994.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Dimension is measured at the maximum bump diameter parallel to primary datum Z .
5. Bump position designation per JESD 95-1, SPP-010.
6. NSMD refers to non-solder mask defined pad design per TB451.